

## REMARKS

### STATUS OF THE CLAIMS

In accordance with the foregoing, the Abstract and claims 1, 2 and 4 have been amended. Claim 3 has been cancelled, and new claim 5 has been added.

Claims 1, 2, 4 and 5 are pending and under consideration. No new matter is being presented and approval of the amended claims and Abstract, and entry of the new claim are respectfully requested.

### CHANGES TO THE ABSTRACT

On page 3, item 6, of the Office Action, the Examiner objects to the Abstract because it exceeds 150 words. The Abstract has been amended herein to comply with the requirements set forth by MPEP §608.01(b).

### OBJECTION TO CLAIM 1

Claim 1 is amended herein to distinctly claim the subject matter of the invention. In light of the amendments to claim 1, it is respectfully submitted that the objection is overcome.

### REJECTIONS OF CLAIMS 1, 2 AND 4 UNDER 35 U.S.C. §102(e) AS BEING ANTICIPATED BY McCORMICK (U.S. PATENT NO. 6,369,448 B1)

The rejections of claims 1, 2 and 4 are respectfully traversed and reconsideration is requested.

McCormick discloses a vertically integrated ("chip-over-chip") semiconductor package. However, McCormick uses two semiconductor chips, i.e., a larger top chip 410 and a smaller bottom chip 412, mounted on the packaging substrate. See column 7, lines 7-10 and Fig. 4.

Contrary to this, according to the semiconductor device recited in claim 1, there is a single semiconductor element 10 and a passive element 30, which is not a semiconductor chip, but an electronic part, such as a capacitor, resistor or inductor. Therefore, the electrical characteristic of such a passive element, for example, a capacitor, which is arranged directly under the central region of the semiconductor element 10 can be improved, since it is possible to reduce effectively the switching noise caused by the capacitor, which would affect the

semiconductor device.

McCormick suggests that top to bottom connections in the bottom chip 412 may also be made by through-hole vias in the chip 412. See column 7, lines 25-27. However, McCormick does not teach or suggest that power supply and ground electrodes of the upper chip are connected to the terminals providing power and grounding on the semiconductor package by through-hole vias.

Claim 1 recites that the power supply (third) and ground (fourth) electrodes of the semiconductor element are connected to the connection pads, providing power and grounding on the wiring board through conductive vias penetrating the passive element arranged in the central region of the semiconductor element. Thus, the electrical characteristic of this device is an improvement over the prior art.

Therefore, it is respectfully submitted that claim 1 patentably distinguishes over McCormick. Claims 2 and 4 depend from claim 1 and inherit its patentable recitations. Thus, it is submitted that claims 2 and 4 also patentably distinguish over the reference.

**REJECTION OF CLAIM 3 FOR OBVIOUSNESS UNDER 35 U.S.C. §103(a) AS BEING UNPATENTABLE OVER McCORMICK**

Claim 3 has been cancelled herein. Thus, it is respectfully submitted that the rejection of claim 3 is moot.

**NEW INDEPENDENT CLAIM 5**

New claim 5 recites similar limitations to those of amended claim 1. Thus, the arguments provided above for amended claim 1 are asserted for new claim 5.

Specifically, McCormick does not teach or suggest a semiconductor device with a single semiconductor element and a passive element, which is not a semiconductor chip, but an electronic part, such as a capacitor, resistor or inductor. Furthermore, McCormick does not discuss providing power and grounding on the wiring board through conductive vias penetrating the passive element arranged in the central region of the semiconductor element.

Therefore, it is respectfully submitted that new claim 5 patentably distinguishes over McCormick.

CONCLUSION

In accordance with the foregoing, it is respectfully submitted that all outstanding objections and rejections have been overcome and/or rendered moot. Further, all pending claims patentably distinguish over the prior art. There being no further outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited.

Finally, if there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

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